

SOT850-1

plastic thermal enhanced ball grid array package; 256 balls;
body 17 x 17 x 1.4 mm; heatsink

25 September 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA256
Package type industry code	HBGA256
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package body material type	P (plastic)
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	19-03-2004
Manufacturer package code	SOT850

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	16.8	17	17.2	mm
package width	16.8	17	17.2	mm
seated height	-	2.12	2.12	mm
package height	1.3	1.4	1.52	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	256	-	



2 Package outline

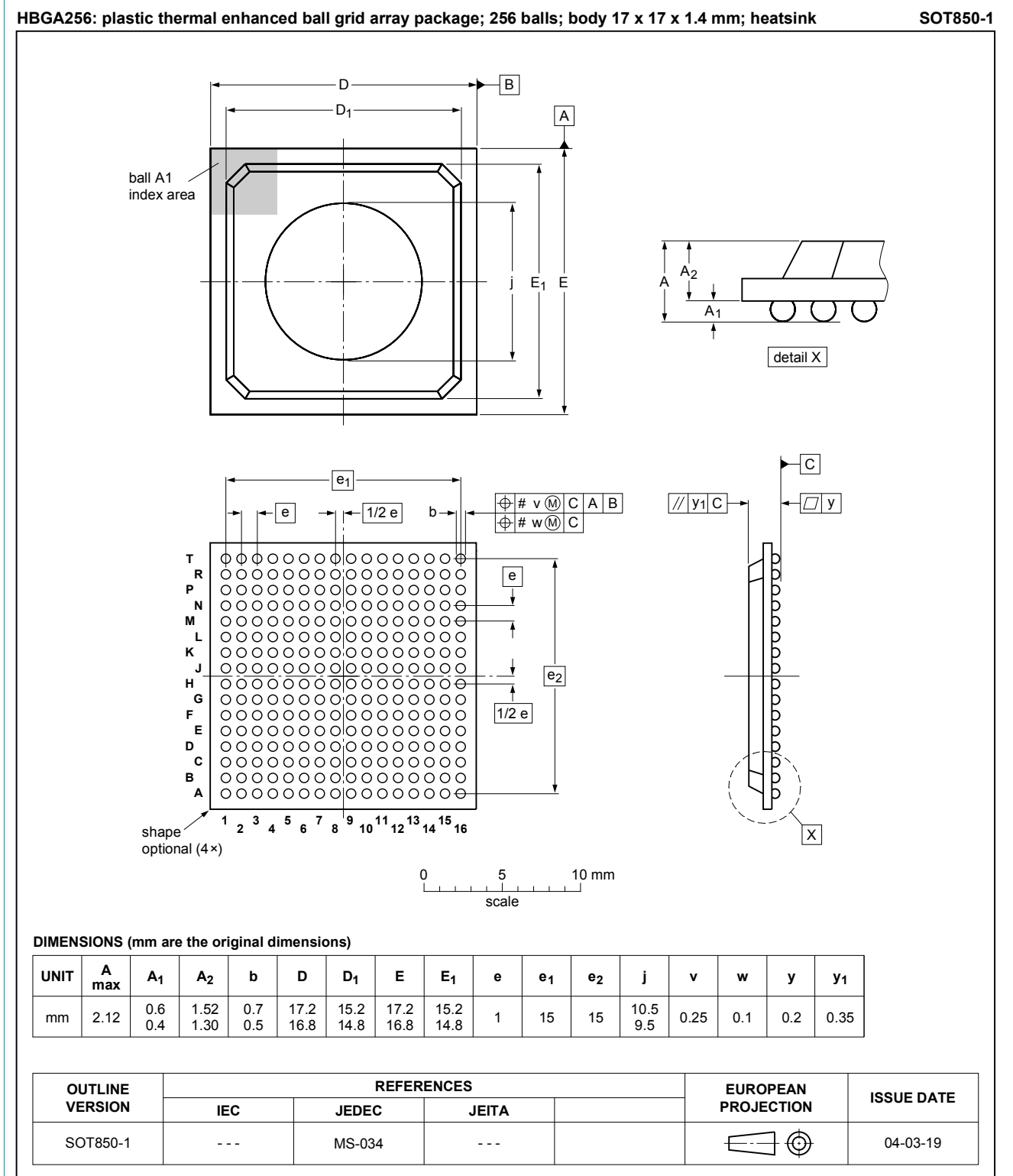


Figure 1. Package outline HBGA256 (SOT850-1)

3 Soldering

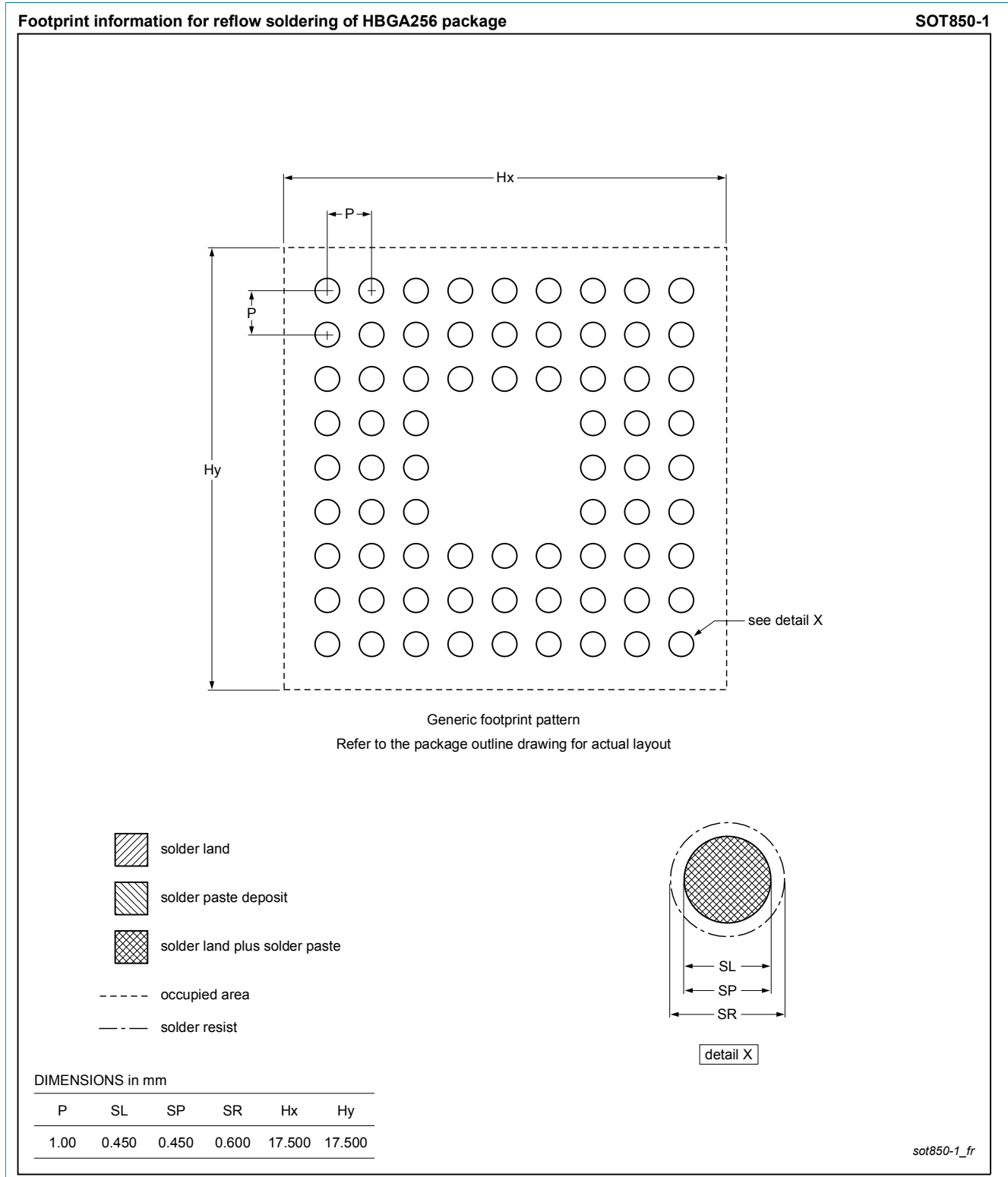


Figure 2. Reflow soldering footprint for HBGA256 (SOT850-1)

4 Legal information

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